

Listing of claims:

1. (Currently Amended) A multi-chip package, comprising:
a plurality of pins; and
first through Nth semiconductor chips, each of which includes,
 an input/output pad,
 an input/output driver coupled to the input/output pad,
 an internal circuit, and
 an internal pad ~~for coupling~~ disposed in a signal path in between the
input/output driver and the internal circuit,
 wherein the internal pads of the first through Nth semiconductor chips are
coupled to each other,
 wherein the input/output pad of the first semiconductor chip directly receives
an input/output signal transmitted via a corresponding one of the pins of the multi-
chip package, and
 wherein the second through Nth semiconductor chips indirectly receive the
input/output signal via the internal pads, which are coupled to each other.
2. (Original) The multi-chip package as claimed in claim 1, wherein the
internal pads are coupled to each other via a common pad installed at a substrate.
3. (Original) The multi-chip package as claimed in claim 1, wherein the
input/output pad of the first semiconductor chip is bonded to one of the pins of the
multi-chip package.
4. (Original) The multi-chip package as claimed in claim 1, wherein each of
the first through (N-1)th semiconductor chips includes a delay circuit for receiving the
input/output signal simultaneously with the internal circuit of the Nth semiconductor
chip.

Claims 5-19 (Cancelled)